

IN THE SPECIFICATION:

Please note that the Abstract shown below is in clean form for clarity.

*Substantive*

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In a socket to test semiconductor die, a recessed socket contact and methods of making contacts that avoid pinching the die contacts are disclosed. The socket contacts allow for smaller socket holes and allow denser contact spacing. In an embodiment, semiconductor fabrication techniques are used to construct a dense array of contacts. A socket contact formation process comprises forming a contact head from a conductive material, forming a contact body from a semiconductive material configured to be electrically conductive; and joining said contact head and said contact body.

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